

In the Claims

Claims 1-68 are canceled.

69. [Currently Amended] A remote intelligent communication device comprising:
a ground plane;
an antenna spaced apart from and interacting with the ground plane, the antenna being substantially electrically insulated from the ground plane;
~~an integrated circuit coupled with the antenna, the integrated circuit including a receiver;~~ transponder circuitry coupled with the antenna;
an encapsulant configured to form a housing about the antenna and the ~~integrated circuit~~ transponder circuitry, the encapsulant comprising an outermost planar surface of the housing; and
~~wherein the integrated circuit includes a modulator configured to communicate using backscatter communications~~ a power source electrically connected with the transponder circuitry and the ground plane.

70. [Previously Presented] The device according to claim 69 wherein the encapsulant encapsulates and contacts the antenna.

71. Canceled.

72. Canceled.

73. [Currently Amended] The device according to claim 69 wherein the encapsulant encapsulates and contacts the ~~integrated circuit~~ transponder circuitry.

74. [Currently Amended] The device according to claim 69 wherein the ~~integrated circuit~~ transponder circuitry comprises radio frequency identification device communication circuitry.

75. [Currently Amended] A communication device comprising:
~~an integrated circuit comprising~~ transponder circuitry operable to communicate an identification signal using backscatter communications responsive to receiving a polling signal;

an antenna coupled with the transponder circuitry; and

a ground plane spaced from the antenna and configured to shield some electromagnetic signals from the antenna and reflect other electromagnetic signals towards the antenna, the ground plane being ~~further configured to electrically couple~~ coupled with a terminal of a power source and provided at a voltage of the terminal.

76. [Previously Presented] The device according to claim 75 wherein the ground plane has a first side facing away from the antenna and configured to shield the some

electromagnetic signals from the antenna, and a second side facing the antenna and configured to reflect the other electromagnetic signals towards the antenna.

77. [Currently Amended] The device according to claim 75 wherein the ~~integrated circuit~~ transponder circuitry is configured to implement radio frequency identification device communications.

78. [Currently Amended] The device according to claim 75 further comprising the power source coupled with the ~~integrated circuit~~ transponder circuitry.

79. [Currently Amended] A method of forming a remote intelligent communication device comprising:

providing a power source;

forming a ground plane;

forming an antenna spaced from the ground plane;

conductively bonding an ~~integrated circuit~~ transponder circuitry with the antenna;

and

electrically coupling the ground plane with the power source to electrically ground the ground plane.

80. [Currently Amended] The method of claim 79 further comprising conductively bonding the ~~integrated circuit~~ transponder circuitry with the ground plane.

81. [Currently Amended] The method of claim 79 further comprising forming a housing to encapsulate and contact the antenna and the ~~integrated circuit~~ transponder circuitry.

82. [Currently Amended] The method of claim 79 wherein the conductively bonding comprises conductively bonding the ~~integrated circuit~~ transponder circuitry configured to implement backscatter communications.

83. [Currently Amended] A method of forming a remote intelligent communication device comprising:

forming a ground plane;

printing an antenna over the ground plane in a substantially electrically insulated relationship with respect to the ground plane;

forming a housing to encapsulate and contact the antenna; and

electrically coupling ~~an integrated circuit~~ transponder circuitry with the antenna.

84. [Previously Presented] The method of claim 83 further comprising providing a dielectric layer intermediate the ground plane and antenna.

85. [Previously Presented] The method of claim 84 further comprising printing at least one conductive connection through the dielectric layer while printing the antenna.

86. [Previously Presented] The method of claim 84 wherein the forming the housing comprises forming the housing to contact a portion of the dielectric layer.

87. [Currently Amended] The method of claim 83 wherein the electrically coupling comprises electrically coupling the ~~integrated circuit~~ transponder circuitry configured to implement backscatter communications.

88. [Currently Amended] A method of forming a radio frequency identification device comprising:

providing a conductive layer;

forming an antenna over the conductive layer;

providing ~~an integrated circuit~~ transponder circuitry over the conductive layer,
wherein the transponder circuitry is configured to communicate using radio frequency identification device communications to identify the radio frequency identification device
~~over the conductive layer;~~

electrically coupling the ~~integrated circuit~~ transponder circuitry with the antenna; and

providing an encapsulant to form the device comprising a substantially void-free mass.

89. [Currently amended] The method of claim 88 further comprising grounding the conductive layer during communications of the transponder circuitry.

90. [Currently Amended] The method of claim 88 wherein the encapsulating comprises:

flowing a flowable encapsulant over the antenna and ~~integrated circuit~~ the transponder circuitry; and
curing the encapsulant.

91. [Previously Presented] The method of claim 79 wherein the antenna comprises a trace of electrically conductive ink.

92. [Previously Presented] The method of claim 83 wherein the printing the antenna comprises printing a trace of electrically conductive ink.

93. [Previously Presented] The method of claim 90 wherein the flowing the flowable encapsulant comprises flowing the flowable encapsulant over an entirety of the antenna.

94. [New] The device according to claim 69 wherein the transponder circuitry includes a modulator configured to communicate using backscatter communications.

95. [New] The device according to claim 69 further comprising an integrated circuit comprising the transponder circuitry.

96. [New] The device according to claim 75 further comprising an integrated circuit comprising the transponder circuitry.

97. [New] The method of claim 79 further comprising providing an integrated circuit comprising the transponder circuitry.

98. [New] The method of claim 83 further comprising providing an integrated circuit comprising the transponder circuitry.

99. [New] The method of claim 88 further comprising providing an integrated circuit comprising the transponder circuitry.

100. [New] The method of claim 88 wherein the providing the encapsulant comprises providing the encapsulant to form the device comprising a solid device which is a void-free mass.